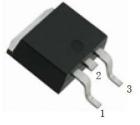
WTR10N600L-HAF

N-Channel Enhancement Mode MOSFET

Features

- Low RDS(ON)
- · Low Gate Charge
- Halogen and Antimony Free(HAF), RoHS compliant

Gate Source



1.Gate 2.Drain 3.Source TO-252 Plastic Package

Application

- · Boost converters
- Synchronous rectifiers
- LED backlighting

Key Parameters

Parameter	Value	Unit	
BV _{DSS}	100	V	
R _{DS(ON)} Max	56 @ V _{GS} = 10 V	m 0	
	60 @ V _{GS} = 4.5 V	mΩ	
V _{GS(th)} typ	1.5	V	
Q _g typ	32 @ V _{GS} = 10 V	nC	

Absolute Maximum Ratings (at Ta = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V _{DS}	100	V	
Gate-Source Voltage	V _{GS}	V _{GS} ± 20		
Drain current $ T_c = 25^{\circ}C $ $ T_c = 100^{\circ}C $	lь	16 10	Α	
Peak Drain Current, Pulsed 1)	I _{DM}	40	Α	
Avalanche Current	I _{AS}	8	Α	
Single Pulse Avalanche Energy 2)	Eas	3.2	mJ	
Power Dissipation T _c = 25°C	P _{tot}	27.8	W	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to + 150	°C	

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Case	Rejc	4.5	°C/W
Thermal Resistance from Junction to Ambient 3)	Reja	50	°C/W

¹⁾ Pulse Test: Pulse Width \leq 100 μs, Duty Cycle \leq 2%, Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)} = 150$ °C.



 $^{^{2)}}$ Limited by $T_{J(MAX)},$ starting T_J = 25 °C, L = 0.1 mH, R_g = 25 $\Omega,\,I_D$ = 8 A, V_{GS} = 10 V.

³⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.

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Characteristics at T_a = 25°C unless otherwise specified

Parameter	Symbol	Min.	Тур.	Max.	Unit
STATIC PARAMETERS	'		•		
Drain-Source Breakdown Voltage at I _D = 250 μA	BV _{DSS}	100	-	-	V
Drain-Source Leakage Current at V _{DS} = 80 V	IDSS	-	-	1	μΑ
Gate Leakage Current at $V_{GS} = \pm 20 \text{ V}$	I _{GSS}	-	-	± 100	nA
Gate-Source Threshold Voltage at V_{DS} = V_{GS} , I_D = 250 μ A	V _{GS(th)}	1.2	-	2.5	V
Drain-Source On-State Resistance at V_{GS} = 10 V , I_D = 5 A at V_{GS} = 4.5 V , I_D = 3 A	R _{DS(on)}	- -	43 -	56 60	mΩ
DYNAMIC PARAMETERS					
Gate resistance at V _{DS} = 0 V, f = 1 MHz	Rg	-	1	-	Ω
Forward Transconductance at $V_{DS} = 5 \text{ V}$, $I_D = 5 \text{ A}$	g fs	-	14	-	S
Input Capacitance at $V_{GS} = 0 \text{ V}$, $V_{DS} = 50 \text{ V}$, $V_{DS} = 1 \text{ MHz}$	C _{iss}	-	1960	-	pF
Output Capacitance at $V_{GS} = 0 \text{ V}$, $V_{DS} = 50 \text{ V}$, $V_{DS} = 1 \text{ MHz}$	Coss	-	50	-	pF
Reverse Transfer Capacitance at $V_{GS} = 0 \text{ V}$, $V_{DS} = 50 \text{ V}$, $f = 1 \text{ MHz}$	C _{rss}	-	46	-	pF
Gate charge total at V_{DS} = 50 V, I_D = 5 A, V_{GS} = 10 V at V_{DS} = 50 V, I_D = 5 A, V_{GS} = 4.5V	Qg	- -	32 15	- -	nC
Gate to Source Charge at V_{DS} = 50 V, I_D = 5 A, V_{GS} = 10 V	Q _{gs}	-	8	-	nC
Gate to Drain Charge at V_{DS} = 50 V, I_D = 5 A, V_{GS} = 10 V	Q_{gd}	-	5	-	nC
Turn-On Delay Time at V_{DS} = 50 V, I_D = 5 A, V_{GS} = 10 V, R_g = 3.3 Ω	t _{d(on)}	-	16	-	nS
Turn-On Rise Time at V_{DS} = 50 V, I_D = 5 A, V_{GS} = 10 V, R_g = 3.3 Ω	tr	-	3	-	nS
Turn-Off Delay Time at V_{DS} = 50 V, I_D = 5 A, V_{GS} = 10 V, R_g = 3.3 Ω	t _{d(off)}	-	14	-	nS
Turn-Off Fall Time at V_{DS} = 50 V, I_D = 5 A, V_{GS} = 10 V, R_g = 3.3 Ω	t _f	-	2	-	nS
Body-Diode PARAMETERS					
Drain-Source Diode Forward Voltage at $I_S = 1$ A, $V_{GS} = 0$ V	V _{SD}	-	-	1.2	V
Body-Diode Continuous Current	ls	-	-	16	Α
Body-Diode Continuous Current, Pulsed	I _{SM}	-	-	40	Α
Body Diode Reverse Recovery Time at I _S = 5 A, di/dt = 100 A / μs	t _{rr}	-	21	-	nS
Body Diode Reverse Recovery Charge at $I_S = 5$ A, di/dt = 100 A / μs	Qrr	-	21	-	nC



Electrical Characteristics Curves

Fig. 2 Typical Transfer Characteristic Fig. 1 Typical Output Characteristic 50 50 TOP V_{GS}=10V V_{GS}=4.5V V_{GS}=4V V_{GS}=3.5V V_{GS}=3V V_{DS}=5V 40 40 Tj=25℃ I_D, Drain Current (A) lo, Drain Current (A) 30 30 Tj=125℃ 20 20 10 0 0 5 Vps, Drain-to-Source Voltage (V) V_{GS}, Gate-Source Voltage (V) Fig. 3 On-Resistance vs Drain Current Fig. 4 On-Resistance vs. Gate Voltage 120 70 ID=5A R_{DS(on)} , Drain-to-Source On Resistance (mΩ) 100 R_{DS(on)}, Drain-to-Source on Resistance (mΩ) 60 Tj=125°C Vgs=4.5V 60 50 40 Tj=25°C Vgs=10V 40 20 0 30 10 15 1 10 0 Vgs, Gate-to-Source Voltage (V) ID, Drain Current (A) Fig. 5 On-Resistance vs.T_j Fig. 6 Typical Forward Characteristic 2.6 2.4 Reverse Drain Current (A) RDS(on), Normalized Drain-to-Source OnResistance 2.2 2 V_{GS}=10V, I_D=5A 10 1.8 Tj=125°C Tj=25°C 1.6 1.4 V_{GS}=4.5V,I_D=3A 1.2 0.8 100 25 150 175 0.2 0.4 1.2 0.8 1.4



V_{SD}, Source-to-Drain Voltage (V)

T_J, Junction Temperature (°C)

Electrical Characteristics Curves

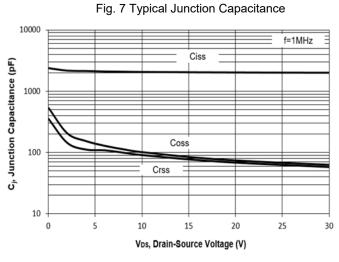


Fig. 8 Drain-Source Leakage Current vs. Tj

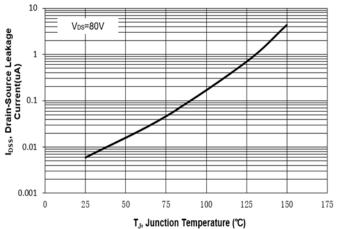


Fig. 9 $V_{(BR)DSS}$ vs. Junction Temperature

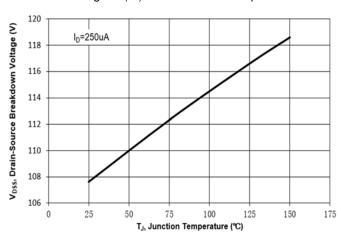


Fig. 10 Gate Threshold Variation vs. T_j

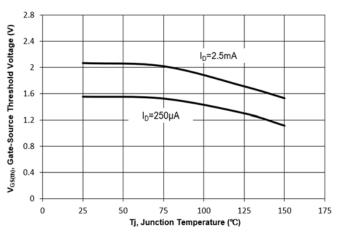


Fig. 11 Gate Charge

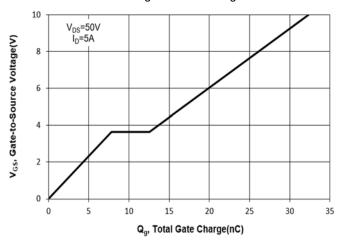
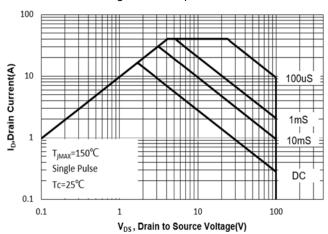


Fig. 12 Safe Operation Area





Electrical Characteristics Curves

Fig.13 Normalized Maximum Transient Thermal Impedance($z_{\text{\tiny OJC}}$)

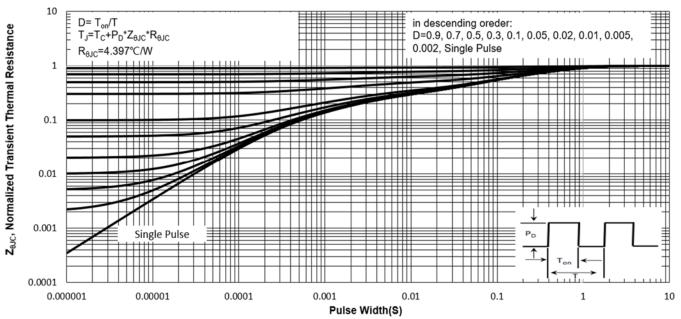
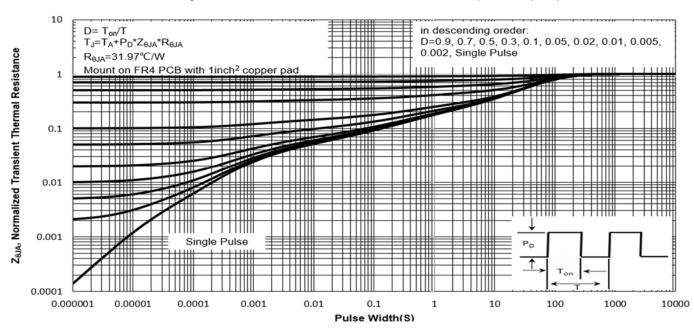


Fig.14 Normalized Maximum Transient Thermal Impedance(z_{OJA})





WTR10N600L-HAF

Test Circuits

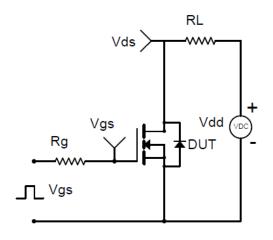


Fig.1-1 Switching times test circuit

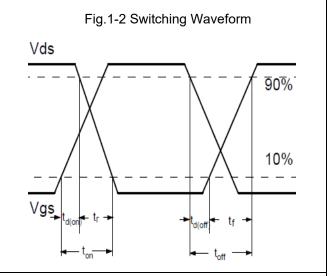


Fig.2-1 Gate charge test circuit

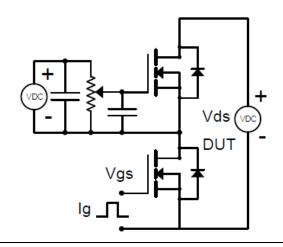


Fig.2-2 Gate charge waveform

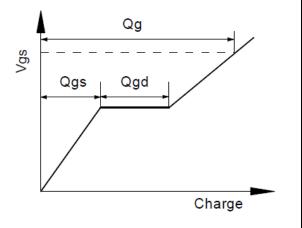


Fig.3-1 Avalanche test circuit

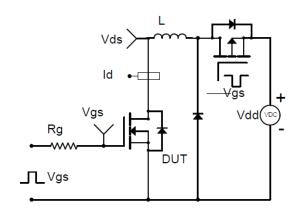
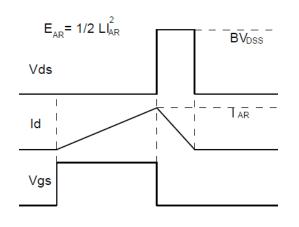


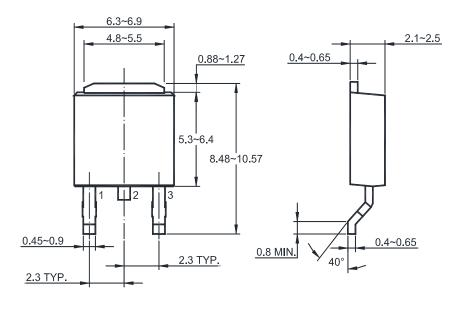
Fig.3-2 Avalanche waveform

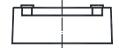




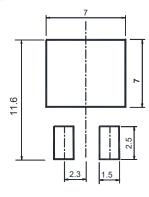
Package Outline (Dimensions in mm)

TO-252





Recommended Soldering Footprint



Packing information

Packago	Tape Width Pitch		tch	Reel Size		Per Reel Packing Quantity
Package (mm)	(mm)	mm	inch	mm	inch	Fel Reel Facking Quantity
TO-252	12	8 ± 0.1	0.315 ± 0.004	330	13	2,500

Marking information

" TR10N600L " = Part No.

" ***** " = Date Code Marking

Font type: Arial





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